

IGBT - Field Stop, Trench

1200 V, 25 A

FGH25T120SMD

Description

Using innovative field stop trench IGBT technology, ON Semiconductor's new series of field stop trench IGBTs offer the optimum performance for hard switching application such as solar inverter, UPS, welder and PFC applications.

Features

- FS Trench Technology, Positive Temperature Coefficient
- High Speed Switching
- Low Saturation Voltage: $V_{CE(sat)} = 1.8 \text{ V @ } I_C = 25 \text{ A}$
- 100% of the Parts Tested for I_{LM} (Note 1)
- High Input Impedance
- This Device is Pb-Free and is RoHS Compliant

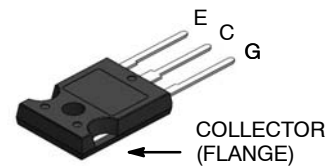
Applications

- Solar Inverter, Welder, UPS & PFC Applications



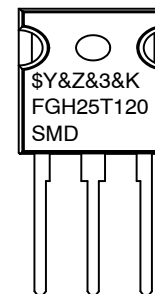
ON Semiconductor®

www.onsemi.com



TO-247-3LD
CASE 340CH

MARKING DIAGRAMS



| | |
|--------------|-------------------------|
| \$Y | = ON Semiconductor Logo |
| &Z | = Assembly Plant Code |
| &3 | = Numeric Date Code |
| &K | = Lot Code |
| FGH25T120SMD | = Specific Device Code |

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

FGH25T120SMD

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$, unless otherwise specified)

| Parameter | Symbol | Ratings | Unit |
|---|-----------|---------------------------|------------------|
| Collector to Emitter Voltage | V_{CES} | 1200 | V |
| Gate to Emitter Voltage | V_{GES} | ± 25 | V |
| Transient Gate to Emitter Voltage | | ± 30 | V |
| Collector Current | I_C | $T_C = 25^\circ\text{C}$ | 50 |
| Collector Current | | $T_C = 100^\circ\text{C}$ | 25 |
| Clamped Inductive Load Current (Note 1) | I_{LM} | $T_C = 25^\circ\text{C}$ | 100 |
| Pulsed Collector Current (Note 2) | I_{CM} | | 100 |
| Diode Continuous Forward Current | I_F | $T_C = 25^\circ\text{C}$ | 50 |
| Diode Continuous Forward Current | | $T_C = 100^\circ\text{C}$ | 25 |
| Diode Maximum Forward Current | I_{FM} | | 200 |
| Maximum Power Dissipation | P_D | $T_C = 25^\circ\text{C}$ | 428 |
| Maximum Power Dissipation | | $T_C = 100^\circ\text{C}$ | 214 |
| Operating Junction Temperature | T_J | -55 to +175 | $^\circ\text{C}$ |
| Storage Temperature Range | T_{stg} | -55 to +175 | $^\circ\text{C}$ |
| Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Seconds | T_L | 300 | $^\circ\text{C}$ |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- $V_{CC} = 600\text{ V}$, $V_{GE} = 15\text{ V}$, $I_C = 100\text{ A}$, $R_G = 23\ \Omega$, Inductive Load
- Limited by T_{jmax}

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|--|-----------------|-------|---------------------------|
| Thermal Resistance, Junction to Case, Max. (IGBT) | $R_{\theta JC}$ | 0.35 | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance, Junction to Case, Max. (Diode) | $R_{\theta JC}$ | 1.4 | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance, Junction to Ambient, Max. | $R_{\theta JA}$ | 40 | $^\circ\text{C}/\text{W}$ |

PACKAGE MARKING AND ORDERING INFORMATION

| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
|----------------|-------------------|------------|-----------|------------|----------|
| FGH25T120SMD | FGH25T120SMD-F155 | TO-247-3LD | - | - | 30 |

ELECTRICAL CHARACTERISTICS OF THE IGBT ($T_C = 25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|-----------|--------|-----------------|-----|-----|-----|------|
|-----------|--------|-----------------|-----|-----|-----|------|

OFF CHARACTERISTICS

| | | | | | | |
|--|------------|--|------|---|-----------|---------------|
| Collector to Emitter Breakdown Voltage | BV_{CES} | $V_{GE} = 0\text{ V}$, $I_C = 250\ \mu\text{A}$ | 1200 | - | - | V |
| Collector Cut-Off Current | I_{CES} | $V_{CE} = V_{CES}$, $V_{GE} = 0\text{ V}$ | - | - | 250 | μA |
| G-E Leakage Current | I_{GES} | $V_{GE} = V_{GES}$, $V_{CE} = 0\text{ V}$ | - | - | ± 400 | nA |

ON CHARACTERISTICS

| | | | | | | |
|---|---------------|--|-----|-----|-----|---|
| G-E Threshold Voltage | $V_{GE(th)}$ | $I_C = 25\text{ mA}$, $V_{CE} = V_{GE}$ | 4.9 | 6.2 | 7.5 | V |
| Collector to Emitter Saturation Voltage | $V_{CE(sat)}$ | $I_C = 25\text{ A}$, $V_{GE} = 15\text{ V}$, $T_C = 25^\circ\text{C}$ | - | 1.8 | 2.4 | V |
| | | $I_C = 25\text{ A}$, $V_{GE} = 15\text{ V}$, $T_C = 175^\circ\text{C}$ | - | 1.9 | - | V |

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ELECTRICAL CHARACTERISTICS OF THE IGBT ($T_C = 25^\circ\text{C}$ unless otherwise noted) (continued)

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|----------------------------------|--------------|---|-----|------|-----|------|
| DYNAMIC CHARACTERISTICS | | | | | | |
| Input Capacitance | C_{ies} | $V_{CE} = 30\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$ | – | 2800 | – | pF |
| Output Capacitance | C_{oes} | | – | 105 | – | pF |
| Reverse Transfer Capacitance | C_{res} | | – | 60 | – | pF |
| SWITCHING CHARACTERISTICS | | | | | | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{CC} = 600\text{ V}, I_C = 25\text{ A},$ $R_G = 23\ \Omega, V_{GE} = 15\text{ V},$ Inductive Load, $T_C = 25^\circ\text{C}$ | – | 40 | – | ns |
| Rise Time | t_r | | – | 45 | – | ns |
| Turn-Off Delay Time | $t_{d(off)}$ | | – | 490 | – | ns |
| Fall Time | t_f | | – | 12 | – | ns |
| Turn-On Switching Loss | E_{on} | | – | 1.74 | – | mJ |
| Turn-Off Switching Loss | E_{off} | | – | 0.56 | – | mJ |
| Total Switching Loss | E_{ts} | | – | 2.30 | – | mJ |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{CC} = 600\text{ V}, I_C = 25\text{ A},$ $R_G = 23\ \Omega, V_{GE} = 15\text{ V},$ Inductive Load, $T_C = 175^\circ\text{C}$ | – | 40 | – | ns |
| Rise Time | t_r | | – | 48 | – | ns |
| Turn-Off Delay Time | $t_{d(off)}$ | | – | 520 | – | ns |
| Fall Time | t_f | | – | 64 | – | ns |
| Turn-On Switching Loss | E_{on} | | – | 2.94 | – | mJ |
| Turn-Off Switching Loss | E_{off} | | – | 1.09 | – | mJ |
| Total Switching Loss | E_{ts} | | – | 4.03 | – | mJ |
| Total Gate Charge | Q_g | $V_{CE} = 600\text{ V}, I_C = 25\text{ A}, V_{GE} = 15\text{ V}$ | – | 225 | – | nC |
| Gate to Emitter Charge | Q_{ge} | | – | 20 | – | nC |
| Gate to Collector Charge | Q_{gc} | | – | 128 | – | nC |

ELECTRICAL CHARACTERISTICS OF THE DIODE ($T_C = 25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|-------------------------------------|-----------|---|-----|------|-----|---------------|
| Diode Forward Voltage | V_{FM} | $I_F = 25\text{ A}, T_C = 25^\circ\text{C}$ | – | 2.8 | 3.7 | V |
| | | $I_F = 25\text{ A}, T_C = 175^\circ\text{C}$ | – | 2.1 | – | V |
| Diode Reverse Recovery Time | t_{rr} | $V_R = 600\text{ V}, I_F = 25\text{ A},$ $di_F/dt = 200\text{ A}/\mu\text{s}, T_C = 25^\circ\text{C}$ | – | 60 | – | ns |
| Diode Peak Reverse Recovery Current | I_{rr} | | – | 6.6 | – | A |
| Diode Reverse Recovery Charge | Q_{rr} | | – | 197 | – | nC |
| Reverse Recovery Energy | E_{rec} | $V_R = 600\text{ V}, I_F = 25\text{ A},$ $di_F/dt = 200\text{ A}/\mu\text{s}, T_C = 175^\circ\text{C}$ | – | 330 | – | μJ |
| Diode Reverse Recovery Time | t_{rr} | | – | 325 | – | ns |
| Diode Peak Reverse Recovery Current | I_{rr} | | – | 13 | – | A |
| Diode Reverse Recovery Charge | Q_{rr} | | – | 2113 | – | nC |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

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TYPICAL PERFORMANCE CHARACTERISTICS

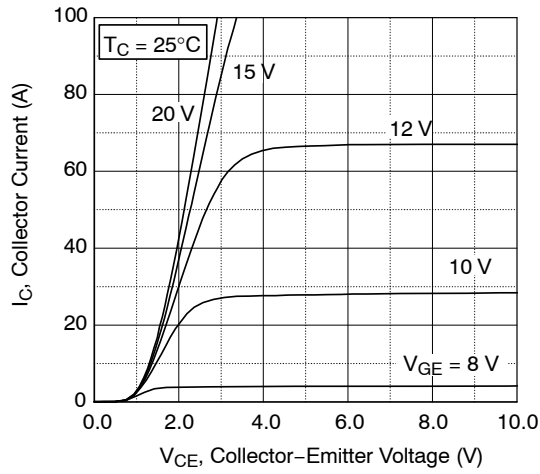


Figure 1. Typical Output Characteristics

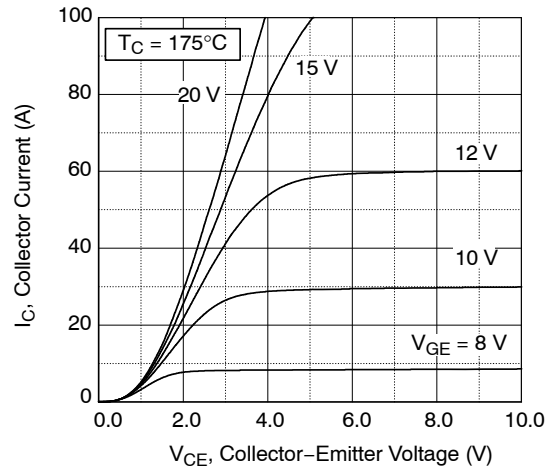


Figure 2. Typical Output Characteristics

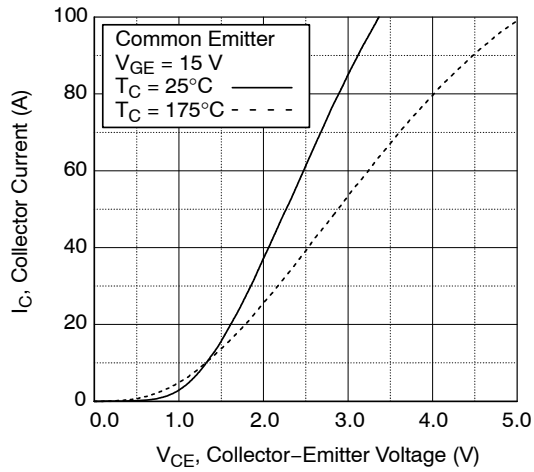


Figure 3. Typical Saturation Voltage Characteristics

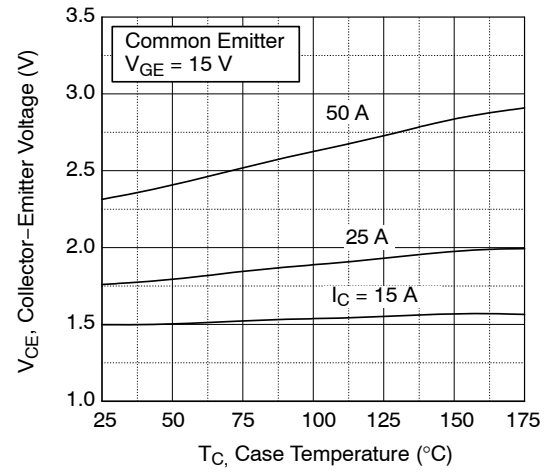


Figure 4. Saturation Voltage vs. Case Temperature at Variant Current Level

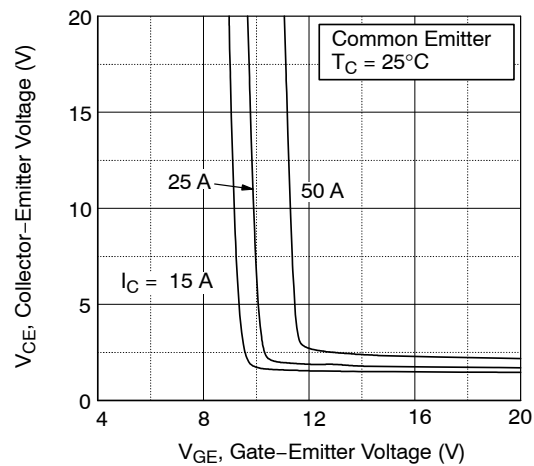


Figure 5. Saturation Voltage vs. V_{GE}

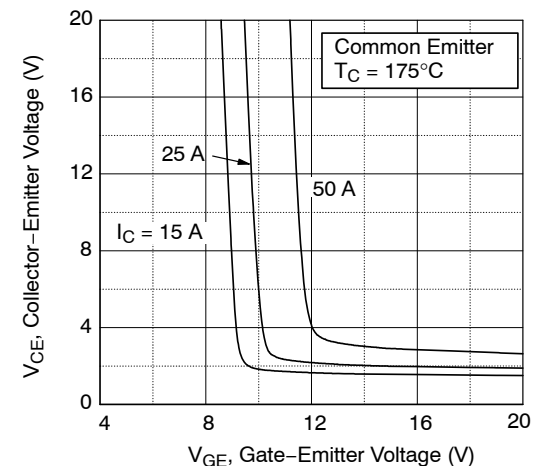


Figure 6. Saturation Voltage vs V_{GE}

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

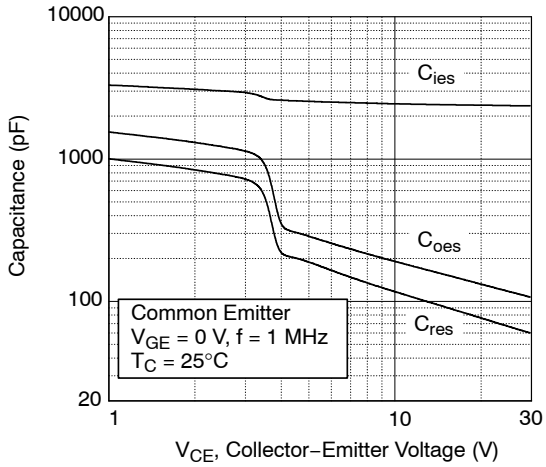


Figure 7. Capacitance Characteristics

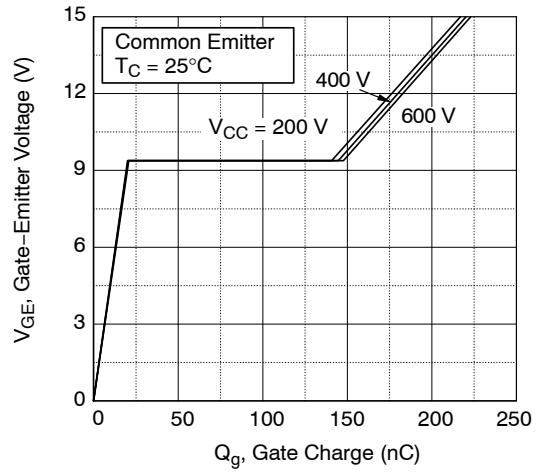


Figure 8. Gate Charge Characteristics

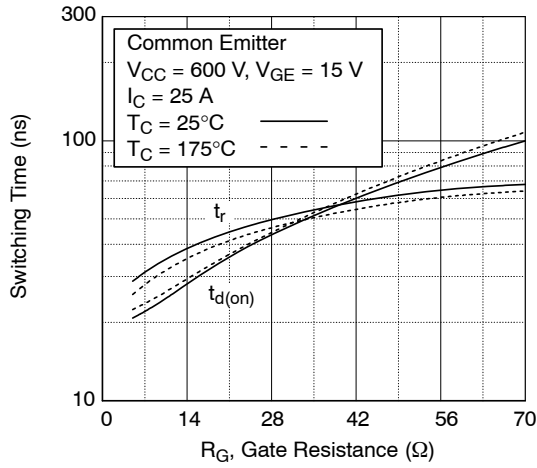


Figure 9. Turn-On Characteristics vs. Gate Resistance

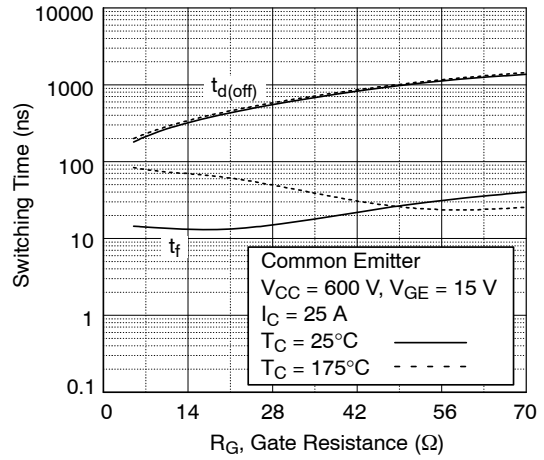


Figure 10. Turn-Off Characteristics vs. Gate Resistance

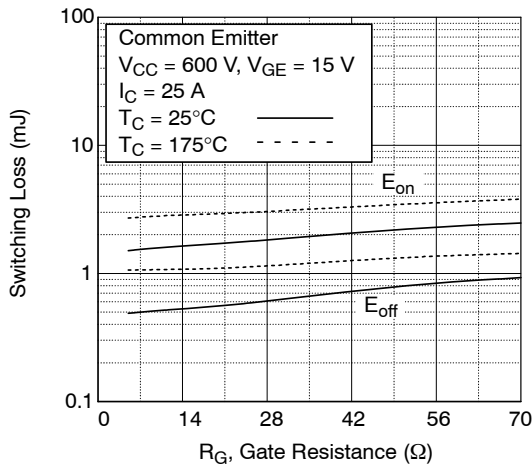


Figure 11. Switching Loss vs. Gate Resistance

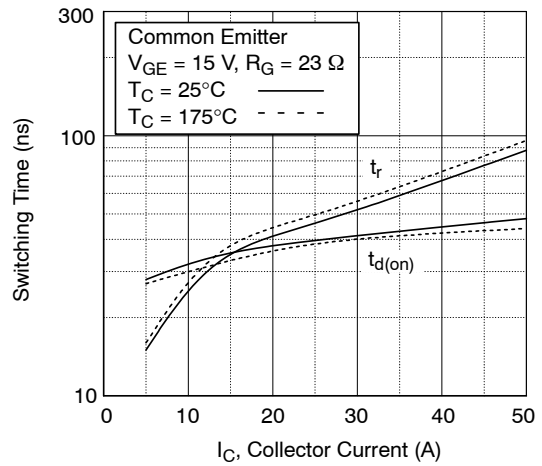


Figure 12. Turn-On Characteristics vs. Collector Current

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TYPICAL PERFORMANCE CHARACTERISTICS (continued)

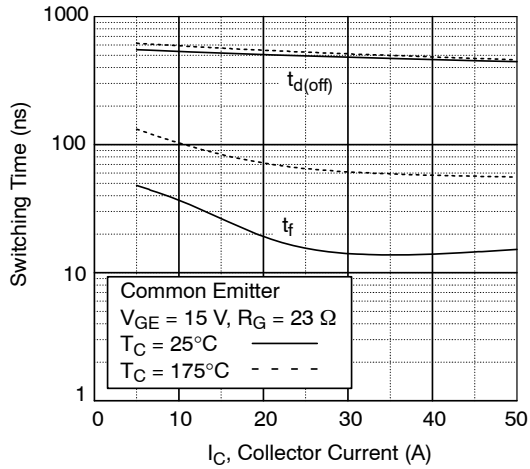


Figure 13. Turn-Off Characteristics vs. Collector Current

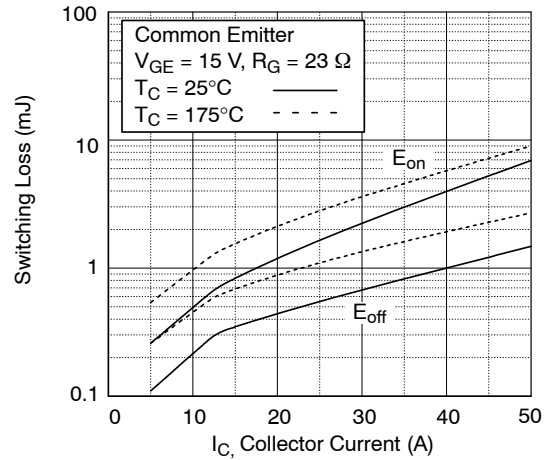


Figure 14. Switching Loss vs. Collector Current

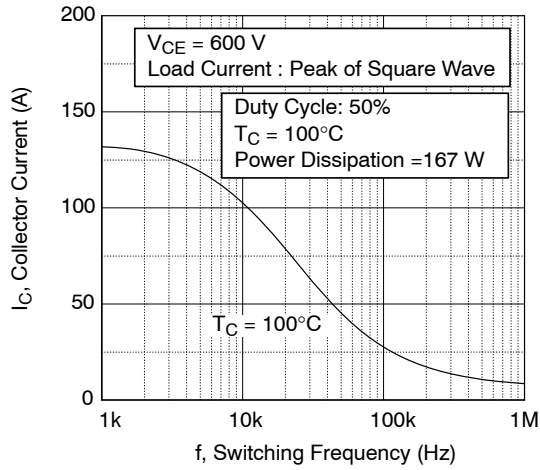


Figure 15. Load Current vs. Frequency

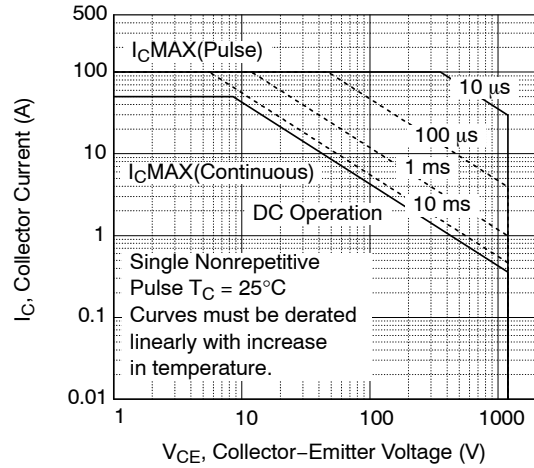


Figure 16. SOA Characteristics

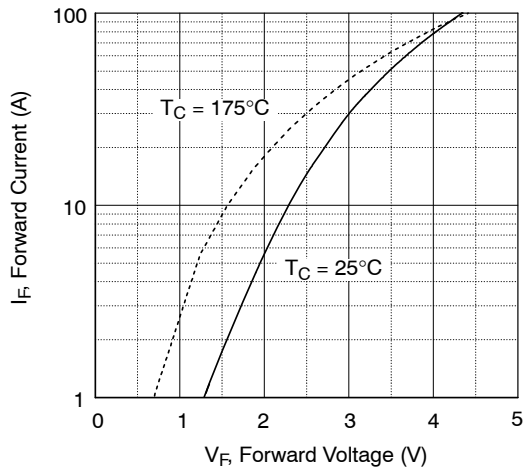


Figure 17. Forward Characteristics

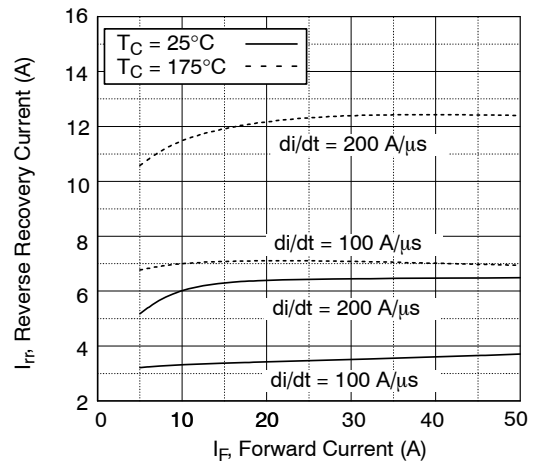


Figure 18. Reverse Recovery Current

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TYPICAL PERFORMANCE CHARACTERISTICS (continued)

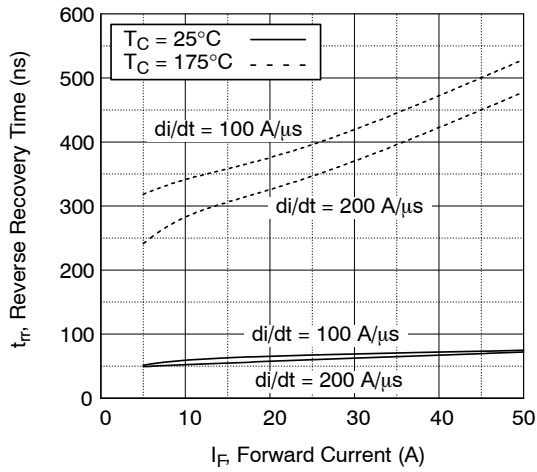


Figure 19. Reverse Recovery Time

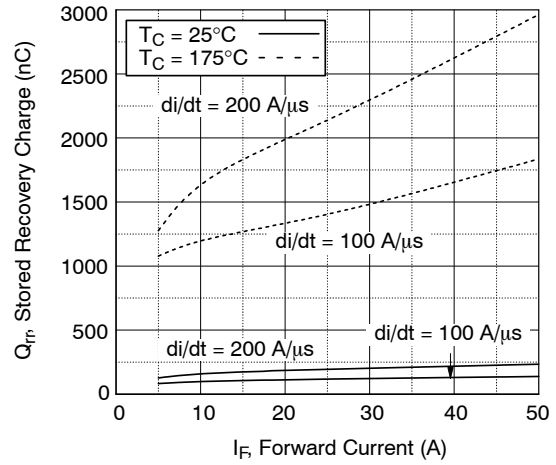


Figure 20. Stored Charge

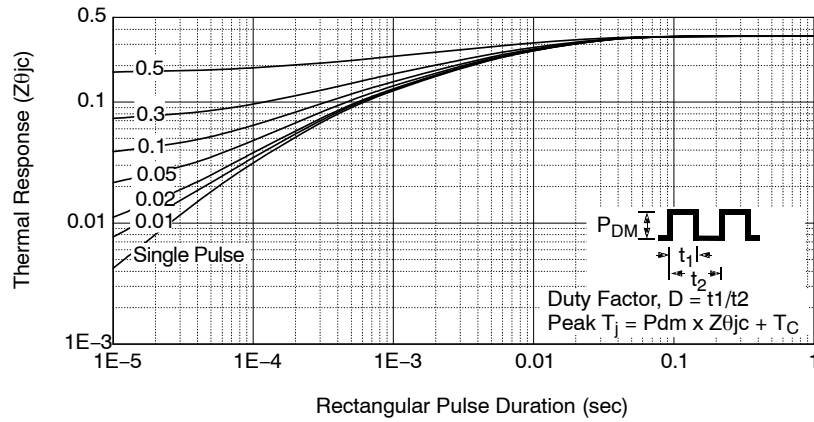


Figure 21. Transient Thermal Impedance of IGBT

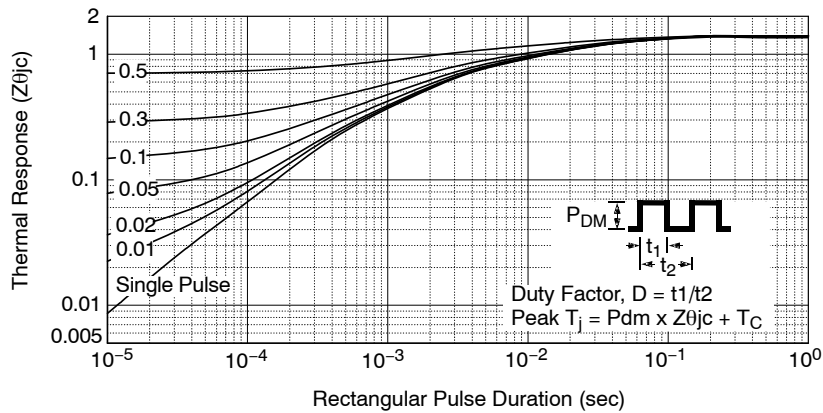


Figure 22. Transient Thermal Impedance of Diode

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



TO-247-3LD
CASE 340CH
ISSUE A

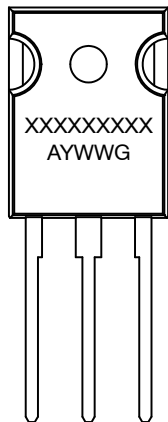
DATE 09 OCT 2019



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 - 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

| DIM | MILLIMETERS | | |
|-----|-------------|-------|-------|
| | MIN | NOM | MAX |
| A | 4.58 | 4.70 | 4.82 |
| A1 | 2.29 | 2.475 | 2.66 |
| A2 | 1.40 | 1.50 | 1.60 |
| D | 20.32 | 20.57 | 20.82 |
| E | 15.37 | 15.62 | 15.87 |
| E2 | 4.96 | 5.08 | 5.20 |
| e | ~ | 5.56 | ~ |
| L | 19.75 | 20.00 | 20.25 |
| L1 | 3.69 | 3.81 | 3.93 |
| ∅P | 3.51 | 3.58 | 3.65 |
| Q | 5.34 | 5.46 | 5.58 |
| S | 5.34 | 5.46 | 5.58 |
| b | 1.17 | 1.26 | 1.35 |
| b2 | 1.53 | 1.65 | 1.77 |
| b4 | 2.42 | 2.54 | 2.66 |
| c | 0.51 | 0.61 | 0.71 |
| D1 | 13.08 | ~ | ~ |
| D2 | 0.51 | 0.93 | 1.35 |
| E1 | 12.81 | ~ | ~ |
| ∅P1 | 6.61 | 6.73 | 6.85 |

| | | |
|------------------|-------------|---|
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| DESCRIPTION: | TO-247-3LD | PAGE 1 OF 1 |

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